



FOR IMMEDIATE RELEASE

HDP User Group Announces New Member Company

Cave Creek, Arizona January 2, 2013. The High Density Packaging Users Group (HDP), located in Arizona, USA, announces that [Indium Corporation](#) has become its newest member.

Indium Corporation manufactures materials for package-on-package, flip-chip, 2.5D and 3D semiconductor assembly, and advanced SMT assembly processes, including semiconductor grade fluxes and solder paste, die-attach wire, and specialty solder spheres.

According to [Dr. Andy Mackie](#), Senior Product Manager for Indium Corporation's semiconductor assembly materials, "We are pleased to be part of a focused group of technology leaders addressing fundamental challenges in the PCB and semiconductor assembly markets."

HDP User Group membership includes system integrators, contract assemblers, and the electronic supply chain focused on the computer and telecommunications industries, which share the same needs. Member companies are the leaders in the use of technologies needed for advanced products and are international in scope, a must for today's global marketplace.

Marshall Andrews Executive Director of HDP User Group said "We are excited to have Indium Corporation as a new member. Indium Corporation will contribute significantly to our electronics assembly programs. HDP User Group has five programs which target the use of new, environmentally-friendly soldering materials. An example is the lead-free materials project, which is in the third phase of an initiative, originally started in 2006, to assess and improve the performance of latest generation PWB laminate systems, after being exposed to simulated Pb-free surface mount soldering conditions."

About Indium Corporation

Indium Corporation is a premier materials manufacturer and supplier to the global electronics, semiconductor, solar, thin-film, and thermal management markets. Products include solders, performs, and fluxes; brazes; sputter targets; indium, gallium, and germanium metals and inorganic compounds; and Reactive NanoFoil®. Founded in 1934, Indium has global technical support and factories located in China, Singapore, South Korea, the United Kingdom, and the USA.



Technology Development in Today's Global Environment

www.hdpug.org

About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development organization based in Cave Creek AZ, dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963